



Material Content Data Sheet



Halogen-Free

Sales Product Name	BSF134N10NJ3 G	Issued	24. February 2022
MA#	MA005701037		
Package	MG-WDSO-2-2	Weight*	50.20 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.788	5.55	5.55	55540	55540
leadframe	non noble metal	copper	7440-50-8	44.951	89.55	89.55	895458	895458
leadfinish	non noble metal	nickel	7440-02-0	0.143	0.28		2841	
	noble metal	silver	7440-22-4	0.567	1.13	1.41	11301	14142
plating	non noble metal	nickel	7440-02-0	0.111	0.22	0.22	2202	2202
solder	non noble metal	copper	7440-50-8	0.003	0.01		52	
	noble metal	silver	7440-22-4	0.016	0.03		312	
	non noble metal	tin	7440-31-5	0.503	1.00	1.04	10021	10385
glue	miscellaneous	miscellaneous	-	0.017	0.03		341	
	plastics	acrylic resin	-	0.134	0.27		2671	
	noble metal	silver	7440-22-4	0.857	1.71	2.01	17071	20083
passivation	plastics	epoxy resin	-	0.110	0.22	0.22	2190	2190
*deviation	< 10%					Sum in total:	100.00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption.

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